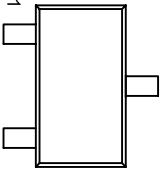
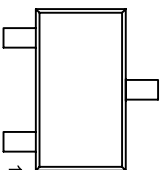




<h3>PRODUCT INFORMATION</h3>					
Customer :					
Device :		Device ID :			
Die Size :		Wafer Material :			
Package Type:		No. of Wires :			
3L SOT-23					
<h3>MATERIAL INFORMATION</h3>					
Leadframe :		Pad Size :			
A194 with Ag spot plating		64x38 mils			
Epoxy :		Wire size :			
Molding Compound :		Lead Finish :			
<h3>MARKING INSTRUCTION</h3>					
TOP :			BOTTOM :		
					
BONDING DIAGRAM NO.					
REF. BONDING DIAGRAM NO.					SCALE not to scale
DRAWN BY :			REVIEWED BY :		
<h3>REVISION NO.</h3>			<h3>APPROVALS</h3>		
REV. #	DESCRIPTION	PCN #	DEPT	APPROVALS	DATE
			CUST		
			QSM		
			QC		
			MFG		
<p style="text-align: center;">SPECIAL INSTRUCTIONS :</p>					
